

HAT2116H

Silicon N Channel Power MOS FET Power Switching

REJ03G1189-0400 (Previous: ADE-208-1575B)

> Rev.4.00 Sep 07, 2005

Features

- Capable of 4.5 V gate drive
- Low drive current
- High density mounting
- Low on-resistance $R_{DS (on)} = 6.3 \text{ m}\Omega \text{ typ. (at } V_{GS} = 10 \text{ V})$

Outline

RENESAS Package code: PTZZ0005DA-A (Package name: LFPAK)

1, 2, 3 Source
4 Gate
5 Drain



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Drain to source voltage	V _{DSS}	30	V
Gate to source voltage	V _{GSS}	±20	V
Drain current	I _D	30	Α
Drain peak current	I _{D (pulse)} Note 1	120	Α
Body-drain diode reverse drain current	I _{DR}	30	Α
Channel dissipation	Pch Note 2	15	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

2. Tc = 25 °C

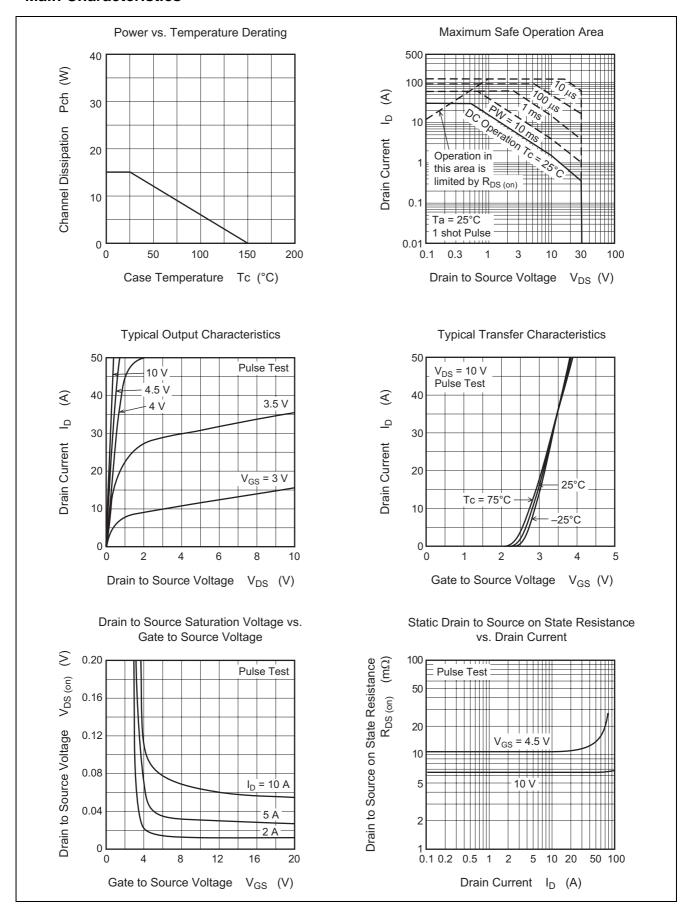
Electrical Characteristics

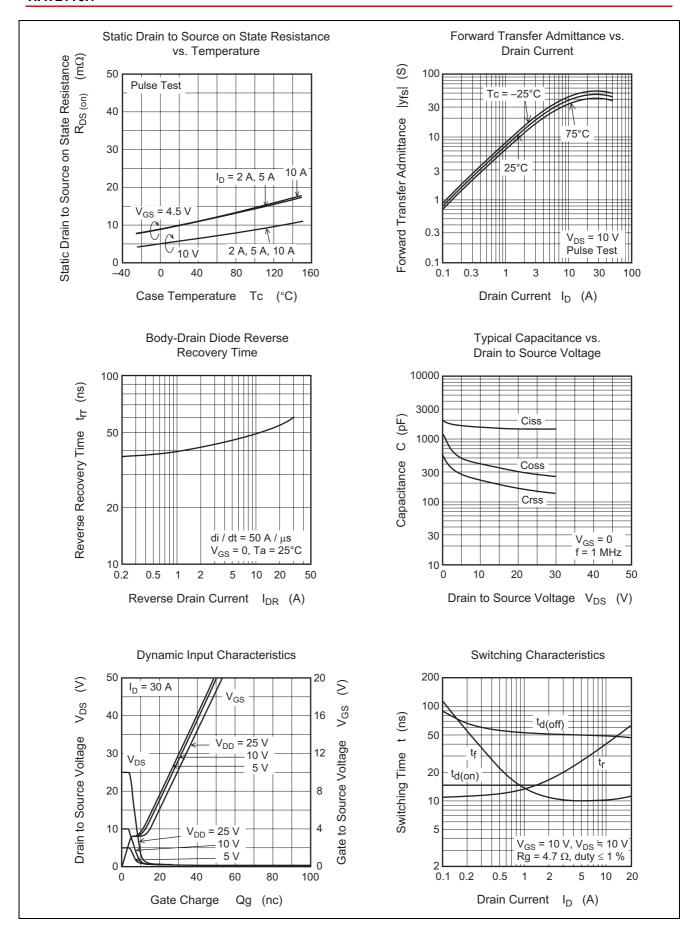
 $(Ta = 25^{\circ}C)$

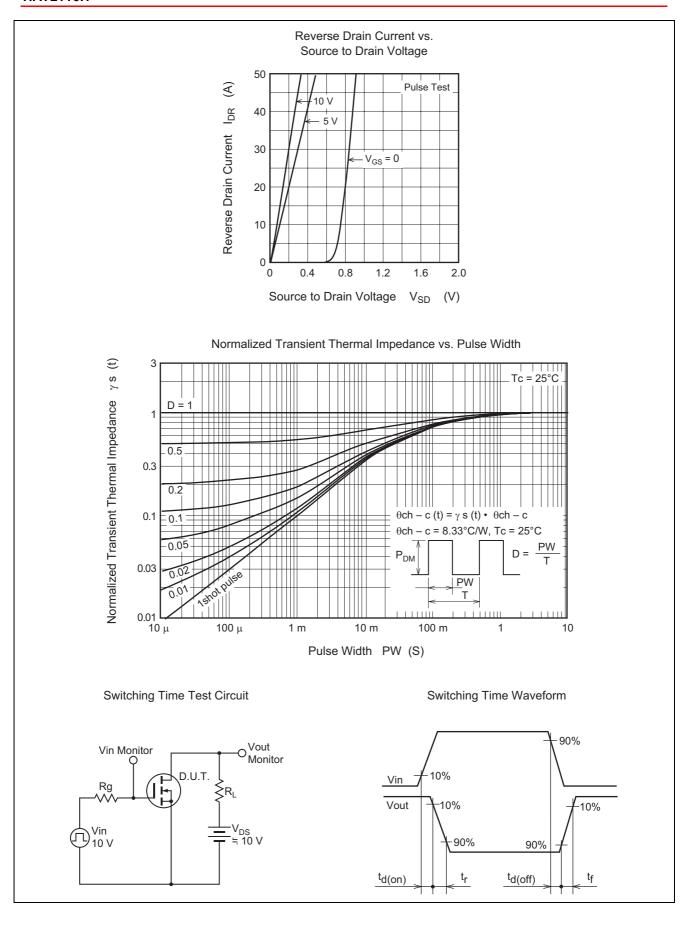
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V _{(BR) DSS}	30	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V _{(BR) GSS}	±20	_		V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}		_	1	μΑ	$V_{DS} = 30 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	V _{GS (off)}	1.0	_	2.5	V	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$
Static drain to source on state resistance	R _{DS (on)}	_	6.3	8.2	mΩ	$I_D = 15 \text{ A}, V_{GS} = 10 \text{ V}^{\text{Note 3}}$
	R _{DS (on)}	_	10.5	15.3	mΩ	$I_D = 15 \text{ A}, V_{GS} = 4.5 \text{ V}^{\text{Note 3}}$
Forward transfer admittance	y _{fs}	27	45	_	S	$I_D = 15 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note 3}}$
Input capacitance	Ciss	_	1650	_	рF	V _{DS} = 10 V
Output capacitance	Coss	_	400	_	рF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	220	_	рF	f = 1 MHz
Total gate charge	Qg	_	26	_	nC	V _{DD} = 10 V
Gate to source charge	Qgs	_	5	_	nC	V _{GS} = 10 V
Gate to drain charge	Qgd	_	5	_	nC	I _D = 30 A
Turn-on delay time	t _{d (on)}	_	15	_	ns	$V_{GS} = 10 \text{ V}, I_D = 15 \text{ A}$
Rise time	t _r	_	55	_	ns	$V_{DD} \cong 10 \text{ V}$
Turn-off delay time	t _{d (off)}	_	48	_	ns	$R_L = 0.5 \Omega$
Fall time	t _f	_	11	_	ns	$Rg = 4.7 \Omega$
Body-drain diode forward voltage	V_{DF}	_	0.85	1.11	V	$I_F = 30 \text{ A}, V_{GS} = 0^{\text{Note } 3}$
Body-drain diode reverse recovery time	t _{rr}	_	60	_	ns	$I_F = 30 \text{ A}, V_{GS} = 0$
						$di_F/dt = 50 A/\mu s$

Note: 3. Pulse test

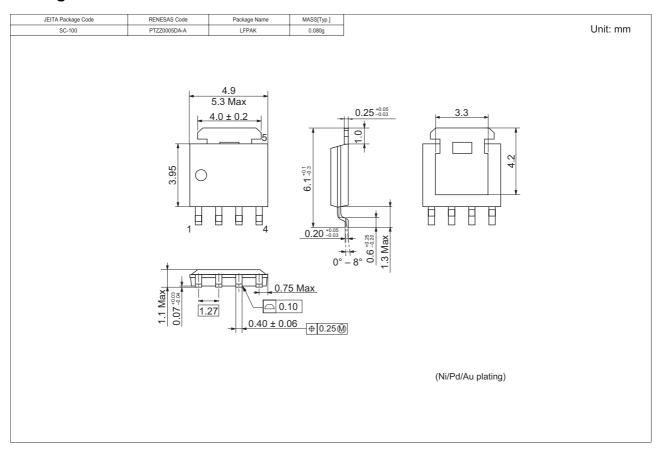
Main Characteristics







Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
HAT2116H-EL-E	2500 pcs	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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